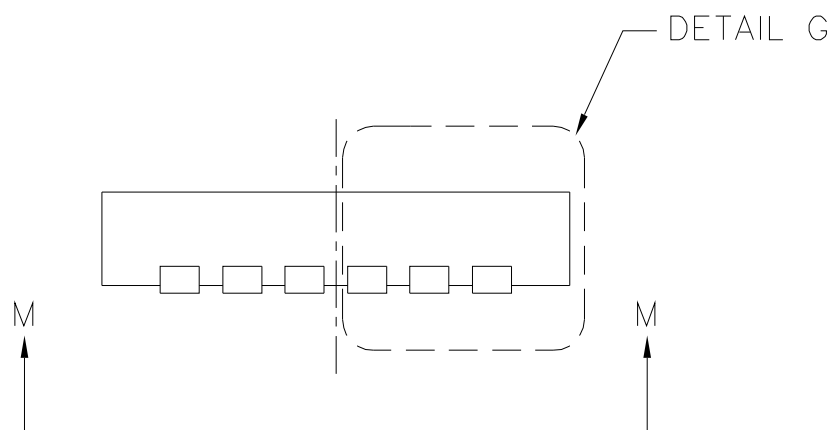
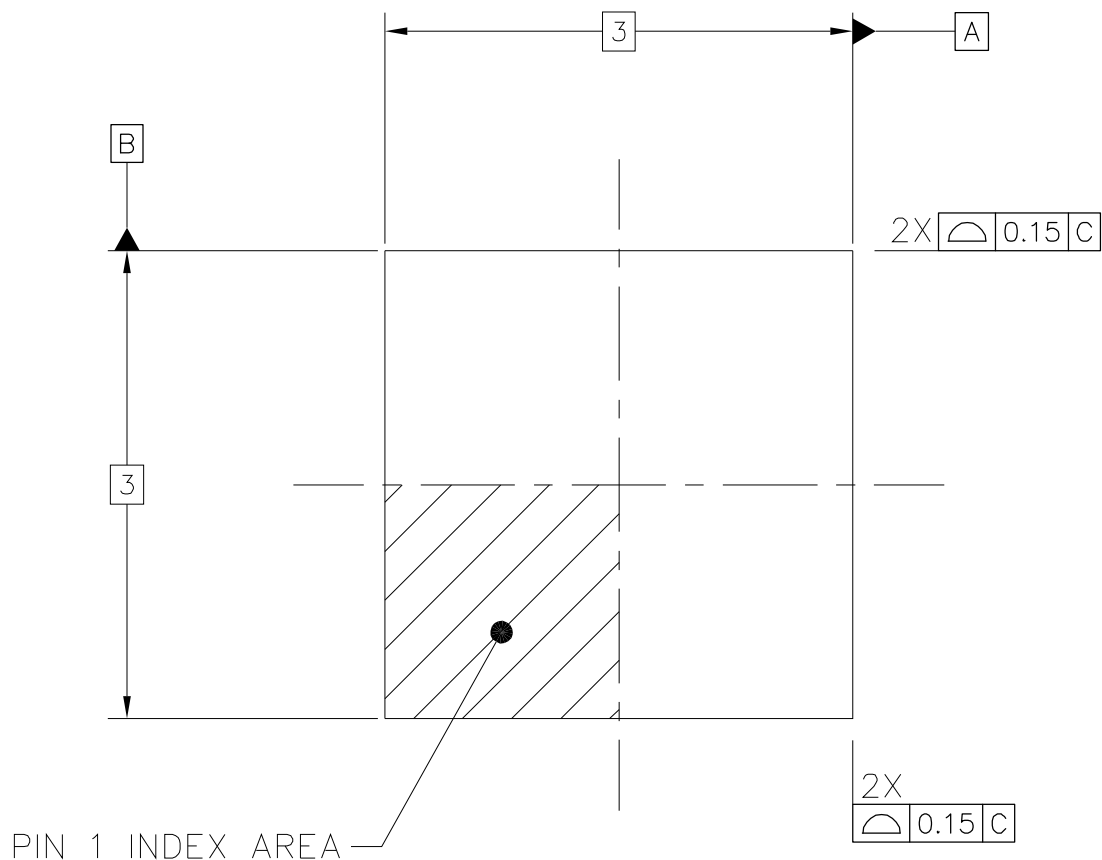
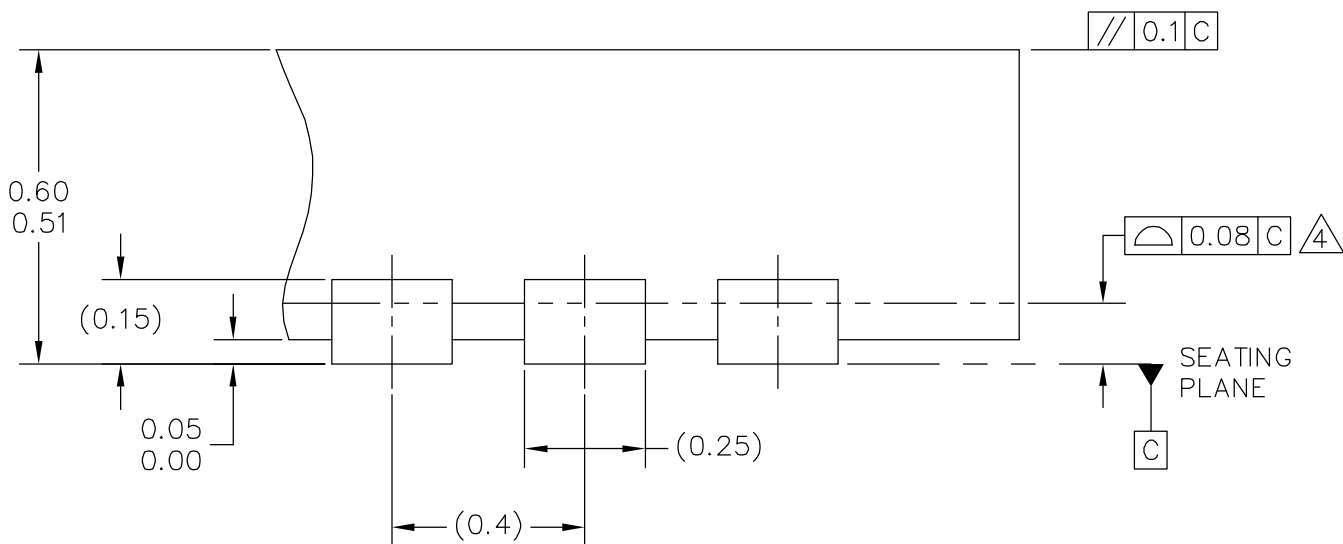
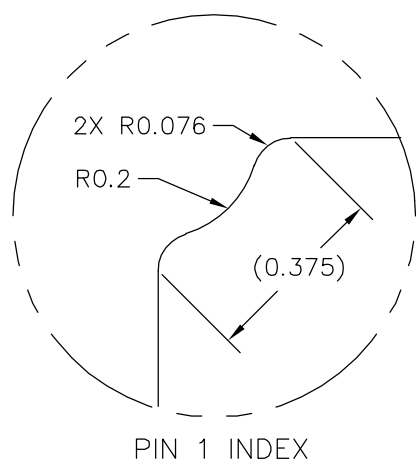




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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 12 TERMINAL, 0.4 PITCH (3 X 3 X 0.6)	DOCUMENT NO: 98ASA10814D REV: A	
	STANDARD: NON-JEDEC	
	SOT1587-1	15 MAR 2016



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	SOT1587-1		15 MAR 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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